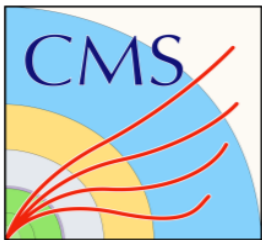


# ATLAS & CMS TIMING DETECTORS

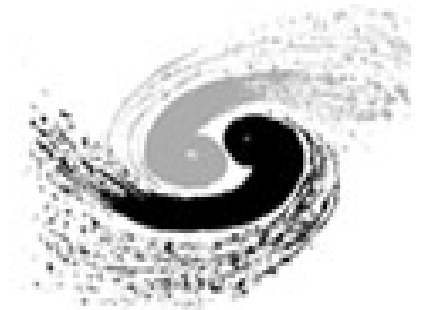


JuanAn García on behalf of ATLAS HGTD  
and CMS MTD Collaborations

Institute of High Energy Physics

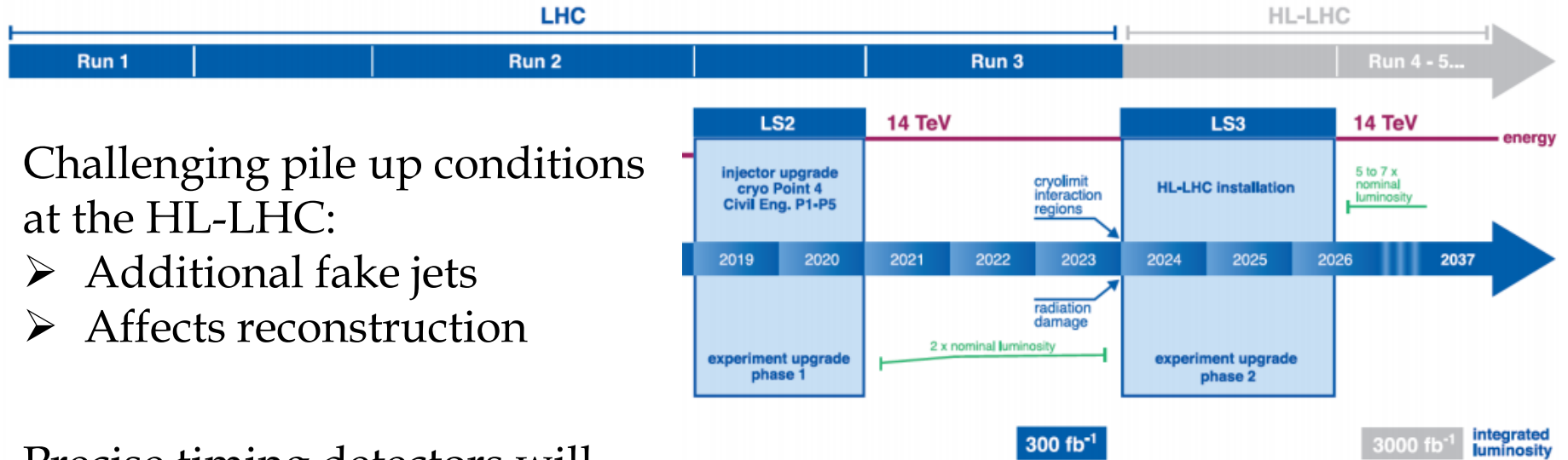
ACES2020

27<sup>th</sup> May 2020



Institute of High Energy Physics  
Chinese Academy of Sciences

## LHC / HL-LHC Plan

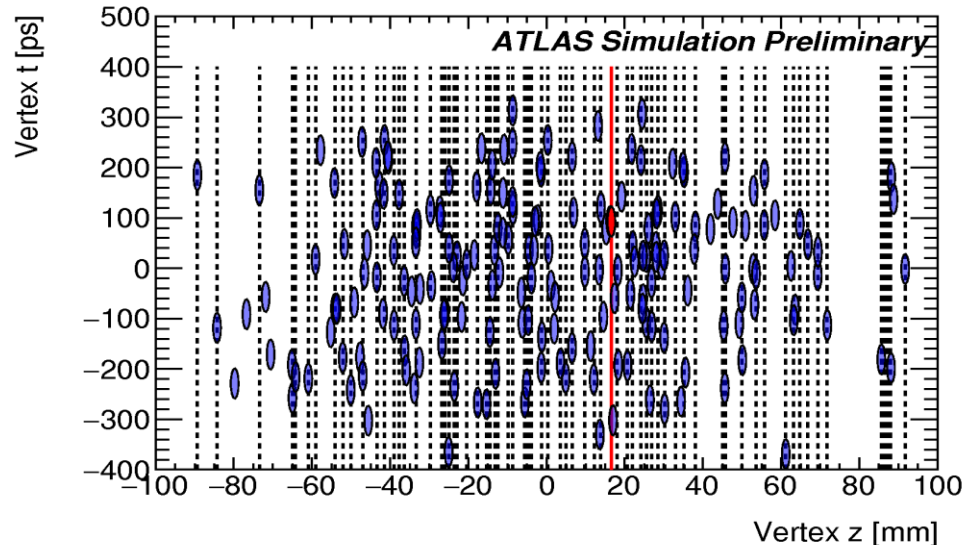


Challenging pile up conditions at the HL-LHC:

- Additional fake jets
- Affects reconstruction

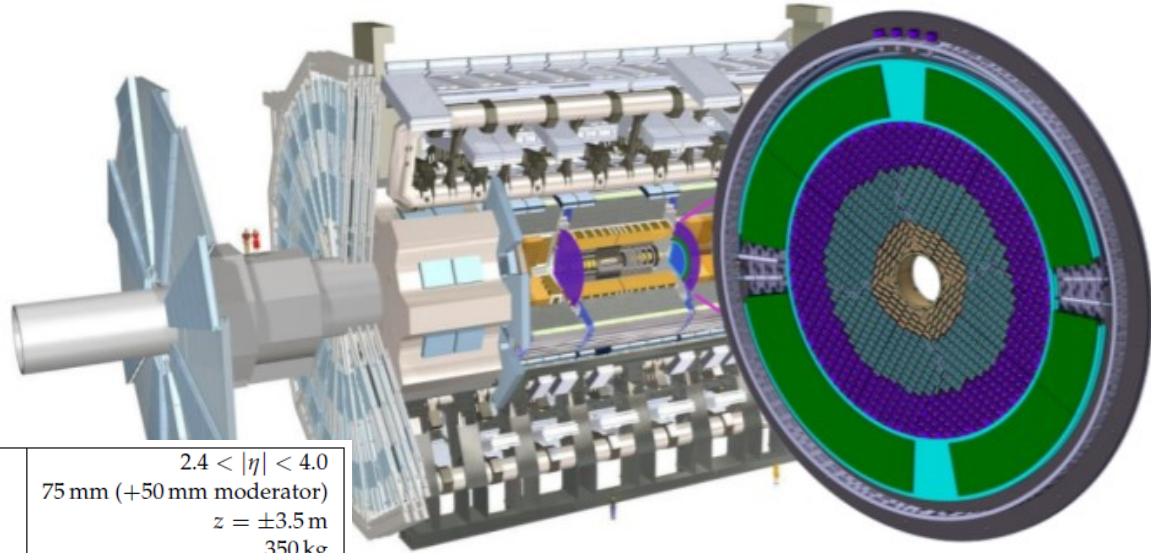
Precise timing detectors will provide time resolution:

- Resolve dense interaction environment with precision timing
- Improve track-to-vertex association

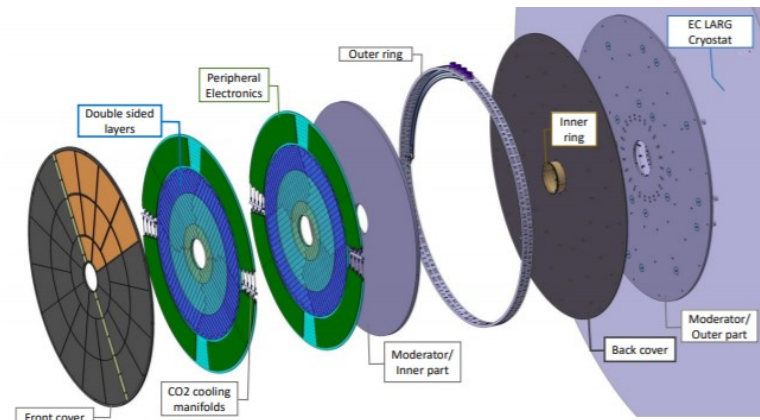


## ATLAS: High Granularity Timing Detector (HGTD):

- Sensor: Large Gain Avalanche Detector (LGAD)
- $\sim 35$  (start)  $\sim 70$  ps timing resolution
- $\sim 2.5 \times 10^{15} n_{eq}/cm^2$  radiation tolerance



Pseudo-rapidity coverage	$2.4 <  \eta  < 4.0$
Thickness in z	75 mm (+50 mm moderator)
Position of active layers in z	$z = \pm 3.5$ m
Weight per end-cap	350 kg
Radial extension:	
Total	$110 \text{ mm} < r < 1000 \text{ mm}$
Active area	$120 \text{ mm} < r < 640 \text{ mm}$
Pad size	$1.3 \text{ mm} \times 1.3 \text{ mm}$
Active sensor thickness	50 $\mu\text{m}$
Number of channels	3.6 M
Active area	6.4 m <sup>2</sup>
Module size	30 x 15 pads (4 cm x 2 cm)
Modules	8032
Collected charge per hit	$> 4.0$ fC
Average number of hits per track	
$2.4 <  \eta  < 2.7$ (640 mm $> r >$ 470 mm)	$\approx 2.1$
$2.7 <  \eta  < 3.5$ (470 mm $> r >$ 230 mm)	$\approx 2.5$
$3.5 <  \eta  < 4.0$ (230 mm $> r >$ 120 mm)	$\approx 2.7$
Average time resolution per hit (start and end of operational lifetime)	
$2.4 <  \eta  < 4.0$	$\approx 35$ ps (start) $\approx 70$ ps (end)
Average time resolution per track (start and end of operational lifetime)	$\approx 30$ ps (start) $\approx 50$ ps (end)

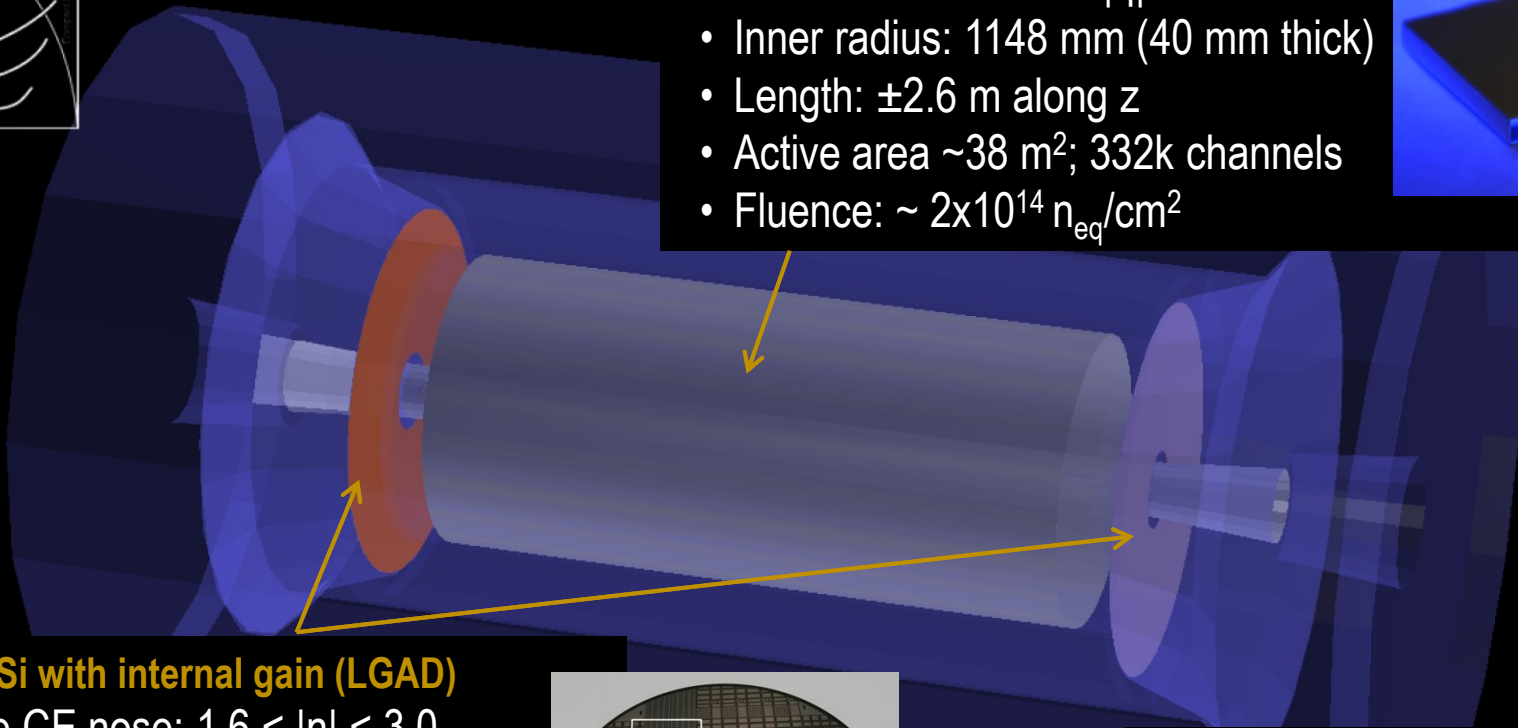


# CMS PRECISION TIMING STRATEGY



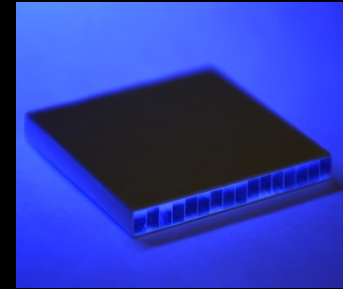
## CMS: MIP Timing Detector (MTD)

## Barrel Timing Layer (BTL)



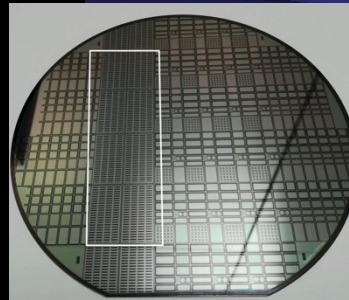
### Barrel: LYSO bars + SiPM readout

- TK / ECAL interface:  $|\eta| < 1.45$
- Inner radius: 1148 mm (40 mm thick)
- Length:  $\pm 2.6$  m along z
- Active area  $\sim 38$  m<sup>2</sup>; 332k channels
- Fluence:  $\sim 2 \times 10^{14}$  n<sub>eq</sub>/cm<sup>2</sup>



### Endcaps: Si with internal gain (LGAD)

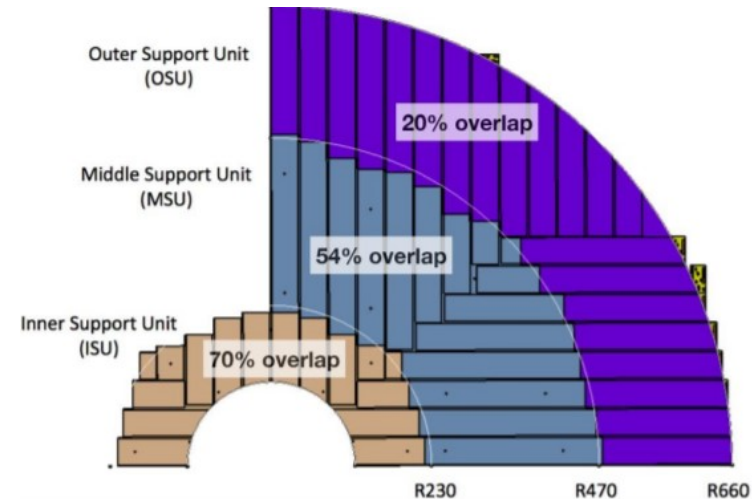
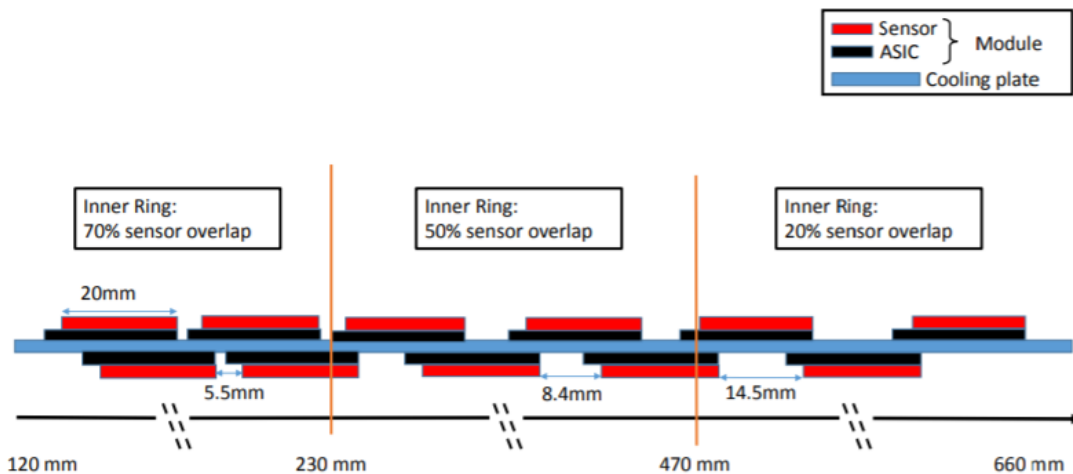
- On the CE nose:  $1.6 < |\eta| < 3.0$
- Radius:  $315 < R < 1200$  mm
- Position in z:  $\pm 3.0$  m (45 mm thick)
- Active area  $\sim 14$  m<sup>2</sup>;  $\sim 8.5$ M channels
- Fluence: up to  $2 \times 10^{15}$  n<sub>eq</sub>/cm<sup>2</sup>



MIP sensitivity with time resolution of 30 ps at HL-LHC start and  $< 60$  ps at 3 ab<sup>-1</sup>

## Endcap Timing Layer (ETL)

- Three rings layout optimised for timing performance and cost
- Module overlap has been optimised for uniformity
- Disk rotation in opposite direction (15-20) to avoid gaps and maximize the hit efficiency
- Each cooling/support disk is separated in two half circular disks
- Support unit made of carbon fibre ensures exact module position and alignment of x and y readout row



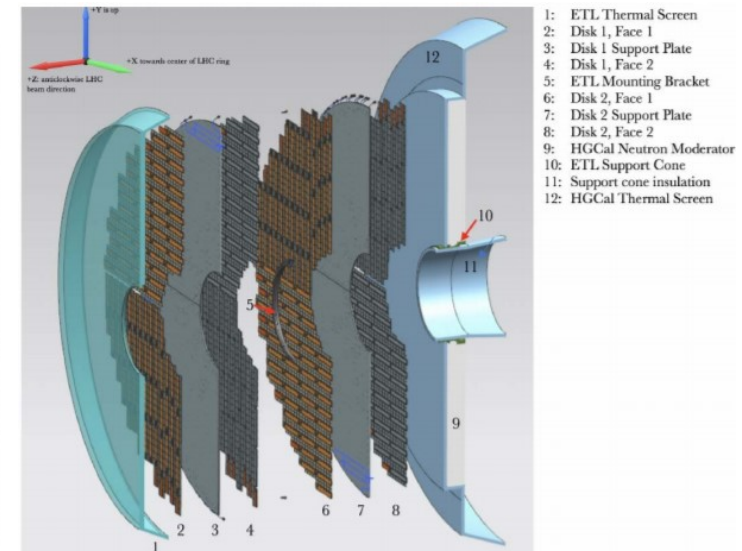
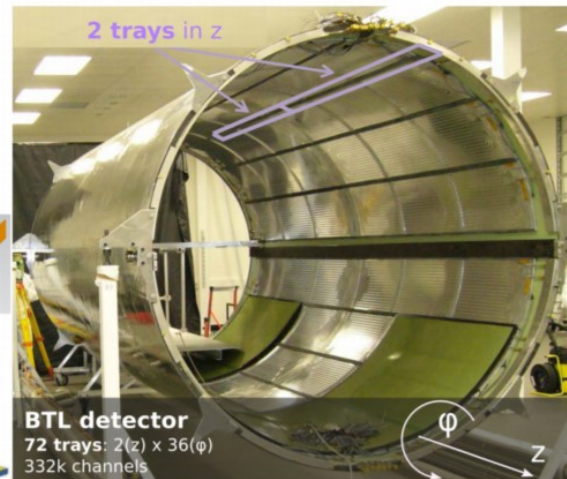
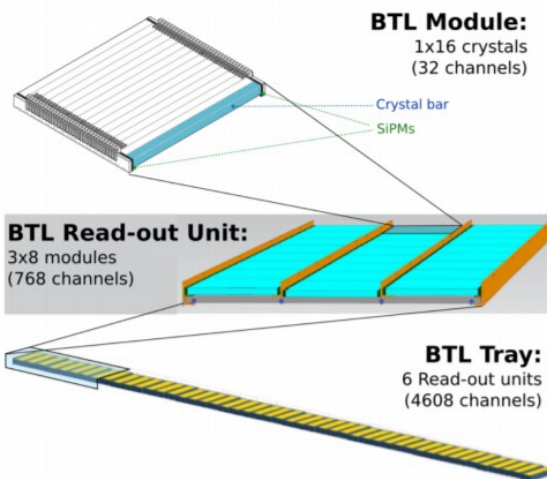


## BTL layout:

- Detector mounted on the inner surface of the Tracker Support Tube share services and schedule with tracker
- Single layer, 40 mm thick, segmented into 72 trays
- Each tray consists of 6 Readout Units with 24 modules each

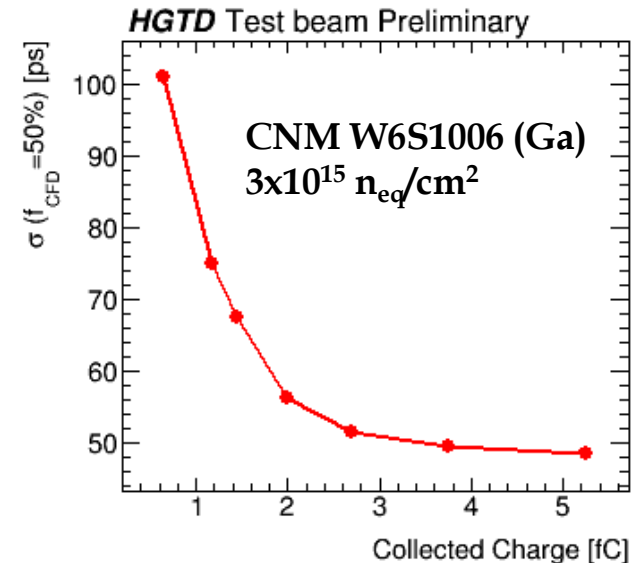
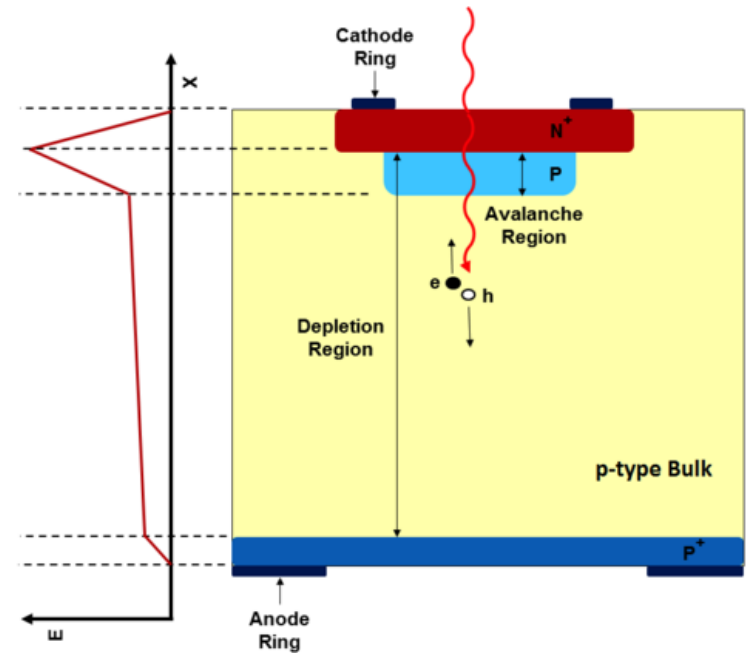
## ETL layout:

- Double mounted on the endcap calorimeter.
- Sensor modules on two sides of support disk.
- Services run across modules in service channels to periphery.
- Separate cold volume.



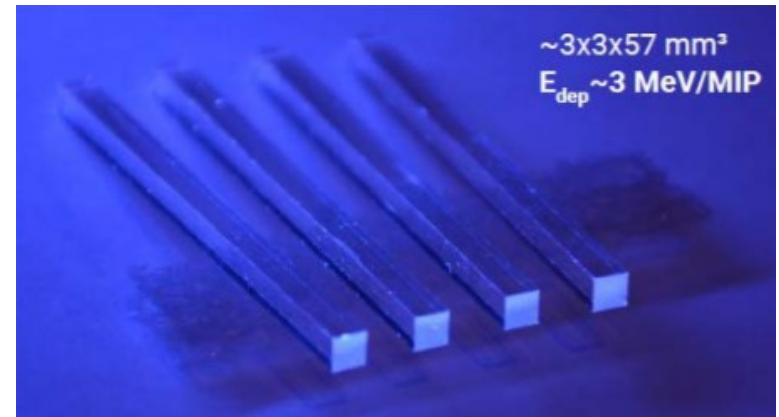
## LGAD sensors:

- Baseline sensor technology for ATLAS HGTD and CMS ETL.
- n-p silicon planar detector + multiplication layer that amplifies the signal
- High E field
- Moderate internal gain (10-50)
- Excellent time resolution  $\sim 30$  ps before irradiation
- New doping materials, substrates and new geometries being studied.
- Prototypes tested from CNM, HPK, BNL, FBK

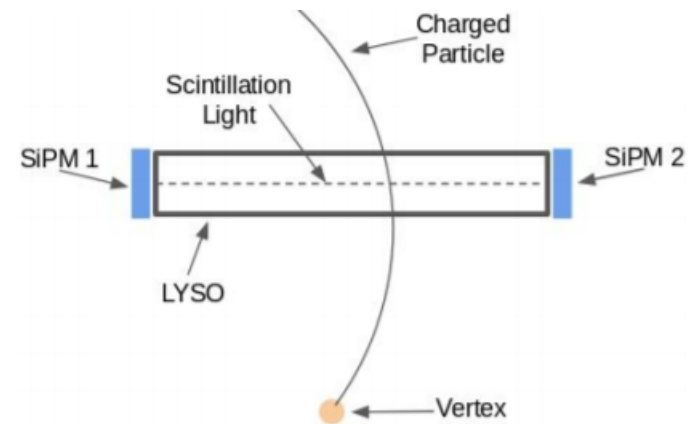


## CMS BTL:

- Cerium doped Lutetium based scintillation crystals (LYSO):
  - Excellent radiation tolerance
  - Density (7.1 g/cm<sup>3</sup>), bright (40k ph/MeV)
  - Fast rise time O(100ps), decay time ~40 ns
- Silicon Photomultipliers as photo-sensors:
  - Compact, insensitive to magnetic fields, fast
  - Optimal SiPM cell size : 15 μm
  - High dynamic range, rad tolerant
  - Photo Detection efficiency : 20-40%



3x3x57mm LYSO crystal bars with two 3x3mm SiPMs glued at each end



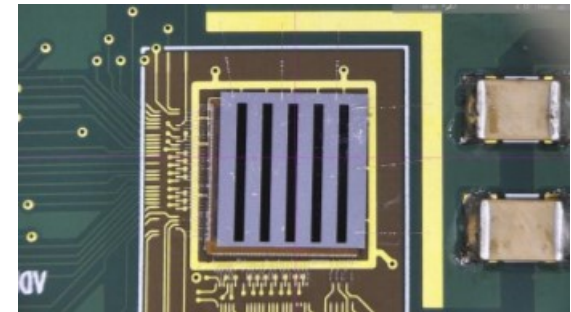
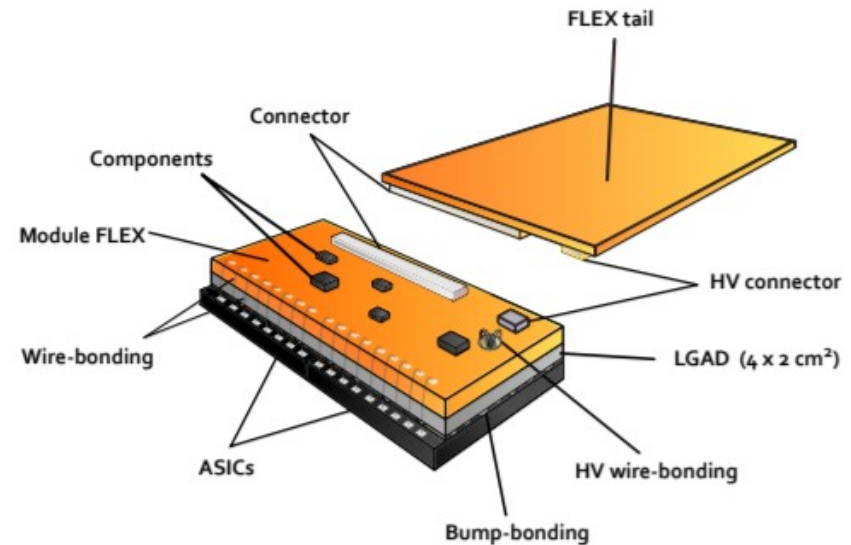


Flexible printed circuit board:

- Bare module glued to small flex
- Routing all connections between ASIC and peripheral on-detector electronic
- Signal lines wire bonded to two ASIC
- 2 layer design with 220  $\mu\text{m}$  thickness

ALTIROC front-end ASIC:

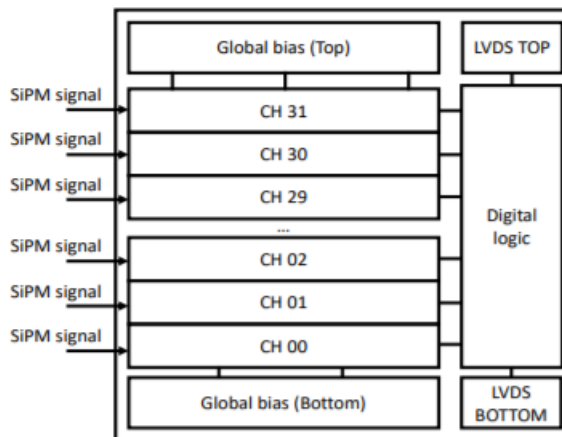
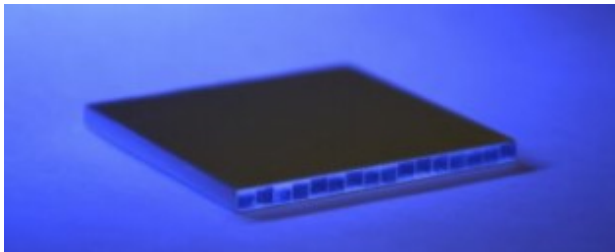
- Radiation hardness  $\sim 2$  MGy
- Target time resolution  $\sim 25$  ps
- Latency up to  $35 \mu\text{s}$  @ 1 MHz trigger
- Low power dissipation
- 15x15 channels (pixels)
- I<sup>2</sup>C link for slow control
- PLL and phase shifter
- Time over threshold (ToT) and Time of Arrival (ToA) information
- Bunch-by-bunch luminosity data in a separate stream



5x5 LGAD sensor bump-bonded to ALTIROC1

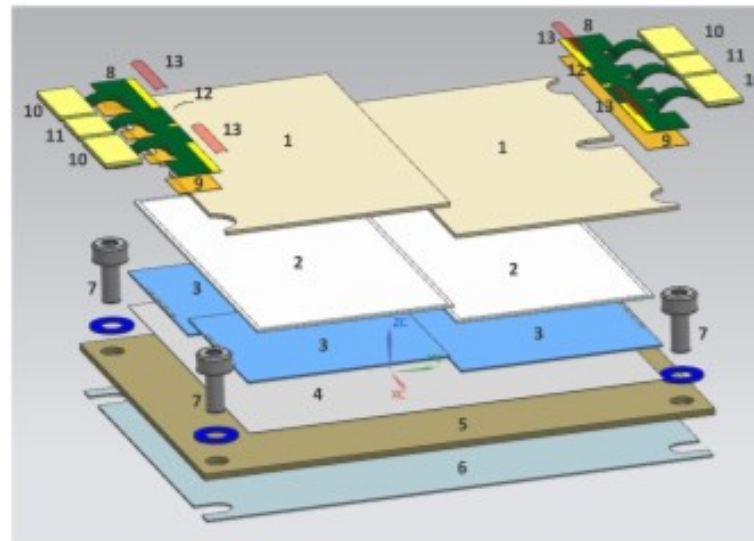
## BTL module:

- 16 LYSO bars + 2 SiPM arrays
- TOFHIR front end ASICs
  - 32 channels
  - Time-to-digital converters  
~25 ps
  - Charge-to-digital converters



## ETL module:

- Bare modules laminated to an AlN substrate
- Flex lines wire bonded to the ASICs
- ETROC front-end ASIC
  - 16×16 channels (pixels)
  - 65 nm technology
  - ASIC contribution to time resolution < 40ps

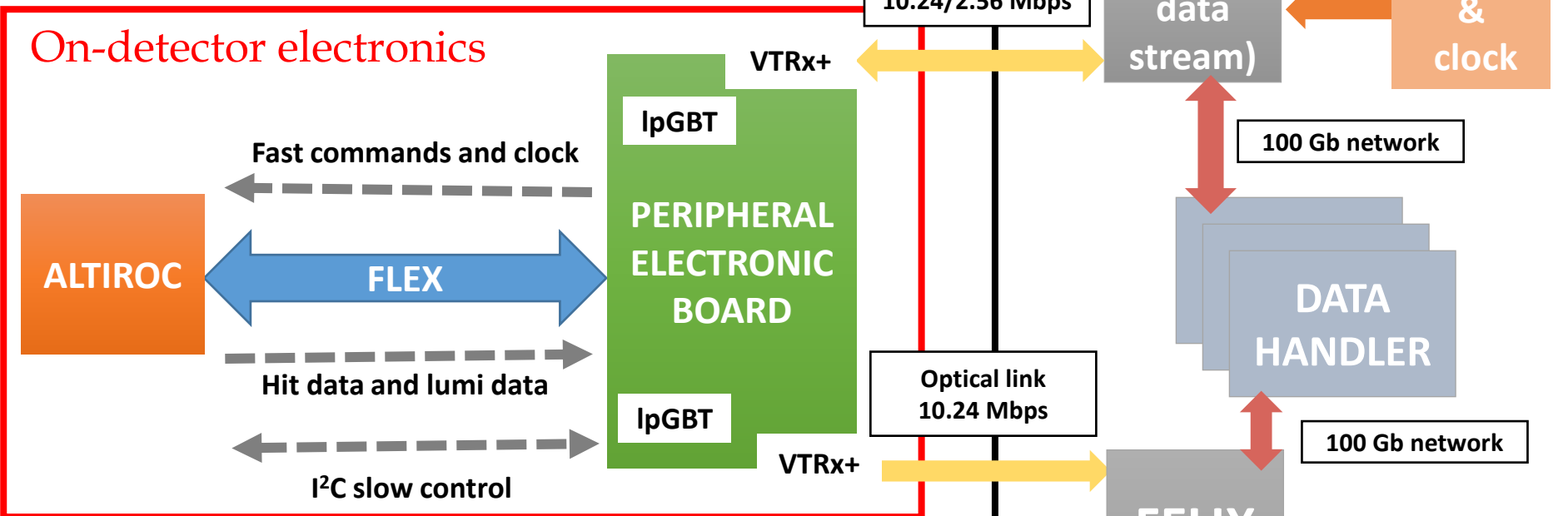


- 1: AlN module cover
- 2: LGAD sensor
- 3: ETL ASIC
- 4: Mounting film
- 5: AlN carrier
- 6: Mounting film
- 7: Mounting screw
- 8: Front-end hybrid
- 9: Adhesive film
- 10: Readout connector
- 11: High voltage connector
- 12: LGAD bias voltage wirebond
- 13: ETROC wirebonds

HGTD readout system:

- On detector electronics:
  - Front-end ASIC (ALTIROC)
  - Peripheral electronic board (PEB)

## On-detector electronics



- Off detector electronics:
  - FELIX (data stream and trigger)
  - Data Handler (event builder)

# CMS MTD READOUT CHAIN

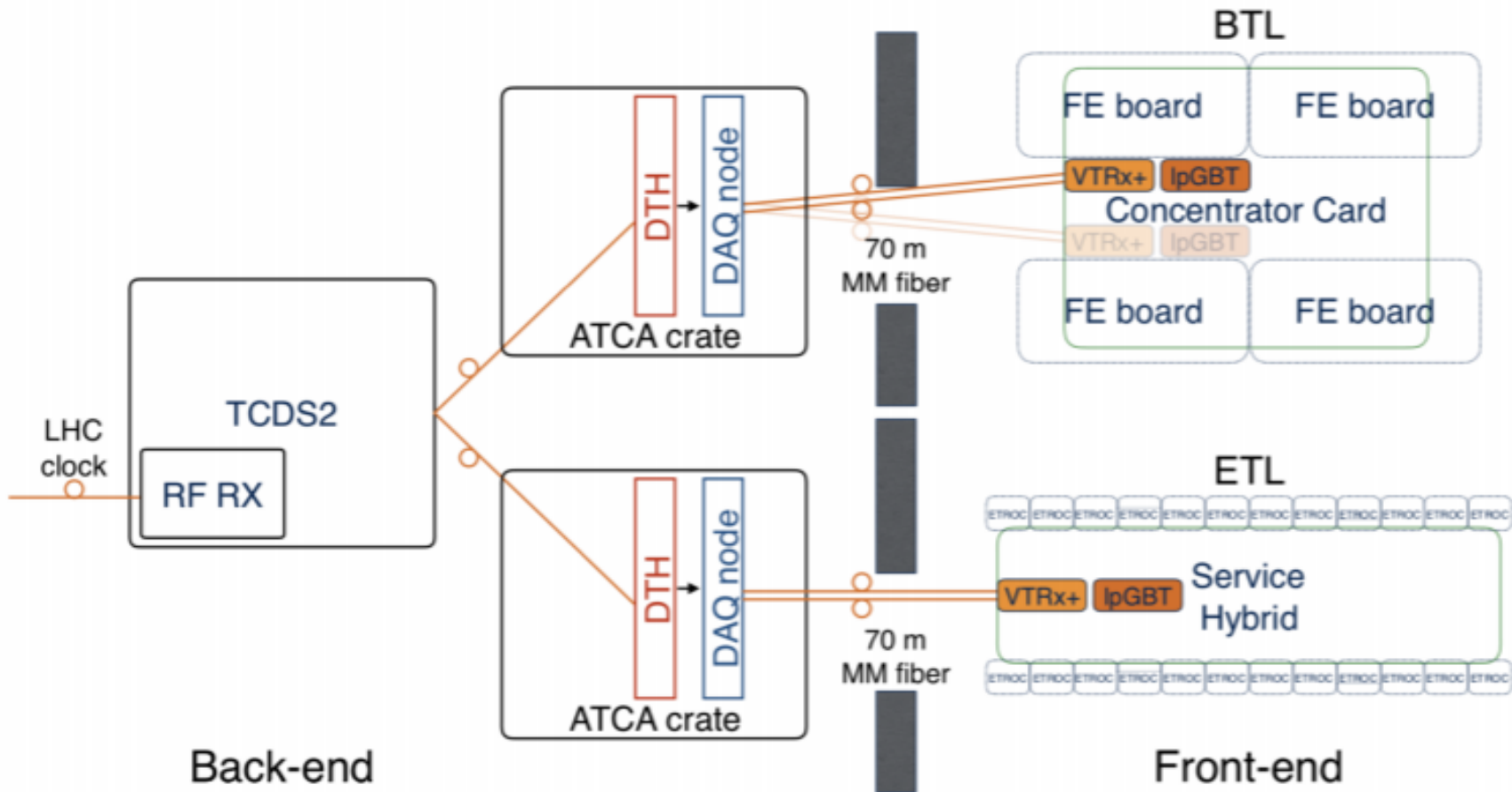


Off-detector electronics:

- DAQ node boards
- DTH board (timing)

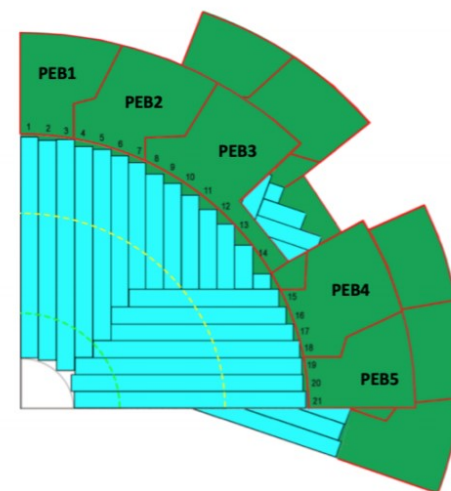
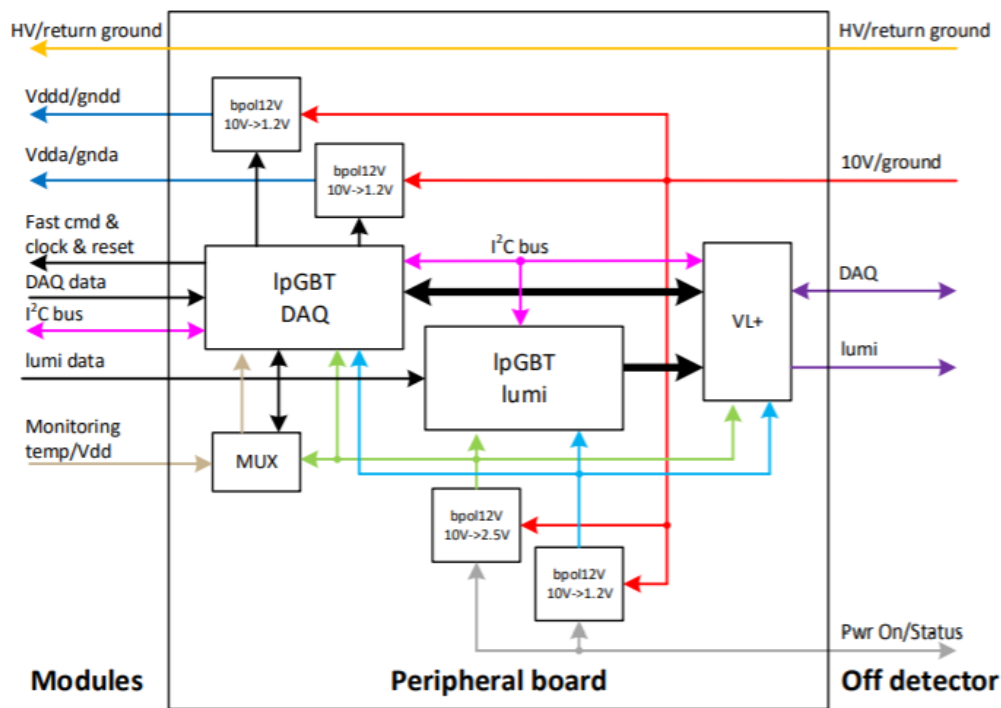
On-detector electronics

- BTL: Concentrator card
- ETL: Hybrid boards



## Peripheral electronic board:

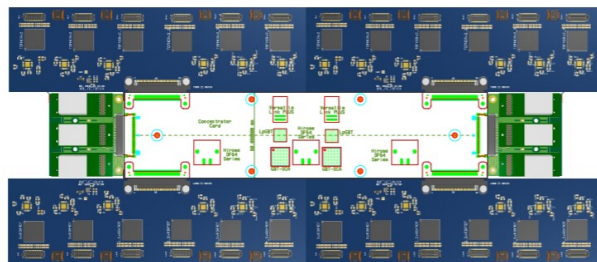
- bpool12VDC-DC converter
- Low power GigaBit Transceiver (lpGBT)
- LV and HV services
- I<sup>2</sup>C bus for slow control and module configuration
- Versatile link Plus (VTRx+): 2.56 and 10.24 Gbps (down/up-link)
- E-link speed 320, 640 and 1280 Mbps (up-link) and and 320 Mbps (down-link)





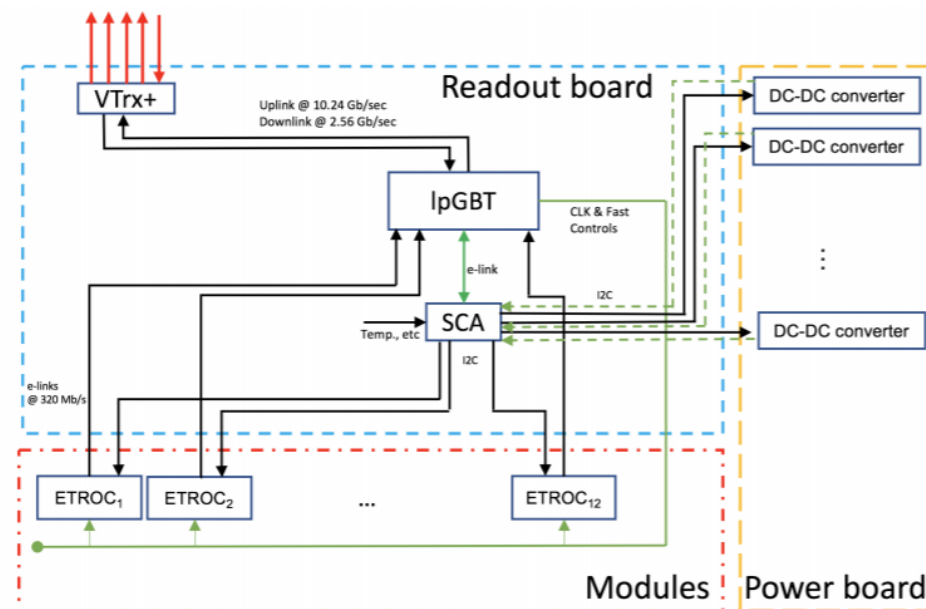
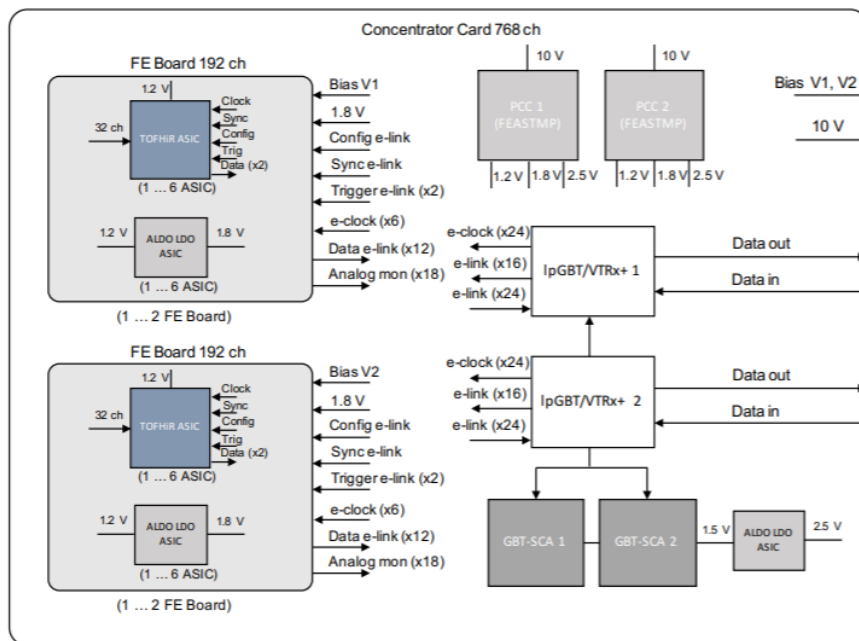
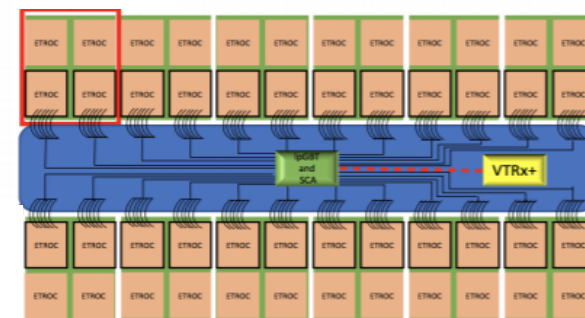
BTL concentrator card:

- Power Control Converter (DC-DC) cards
- GBT-SCA chip for slow control
- lpGBT
- VTRx+



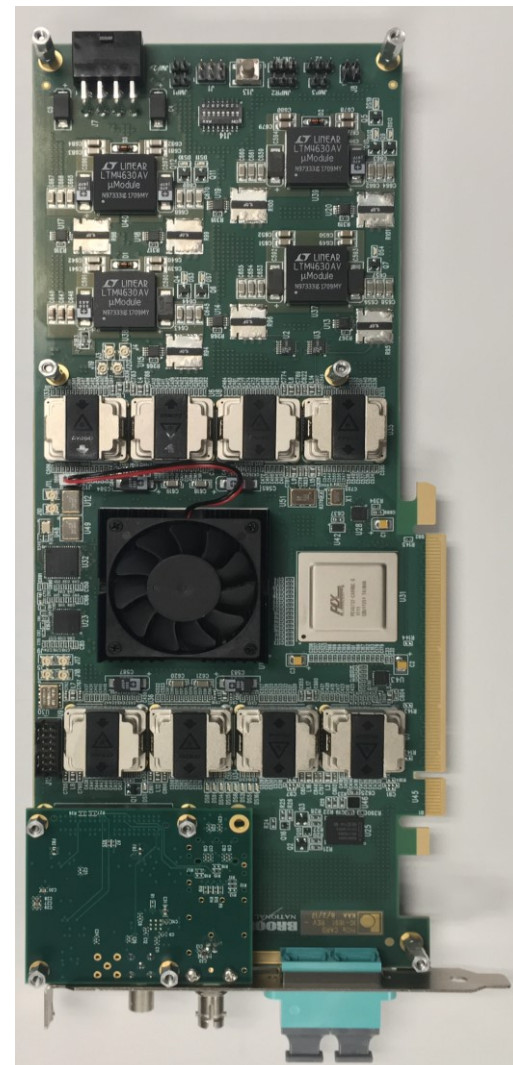
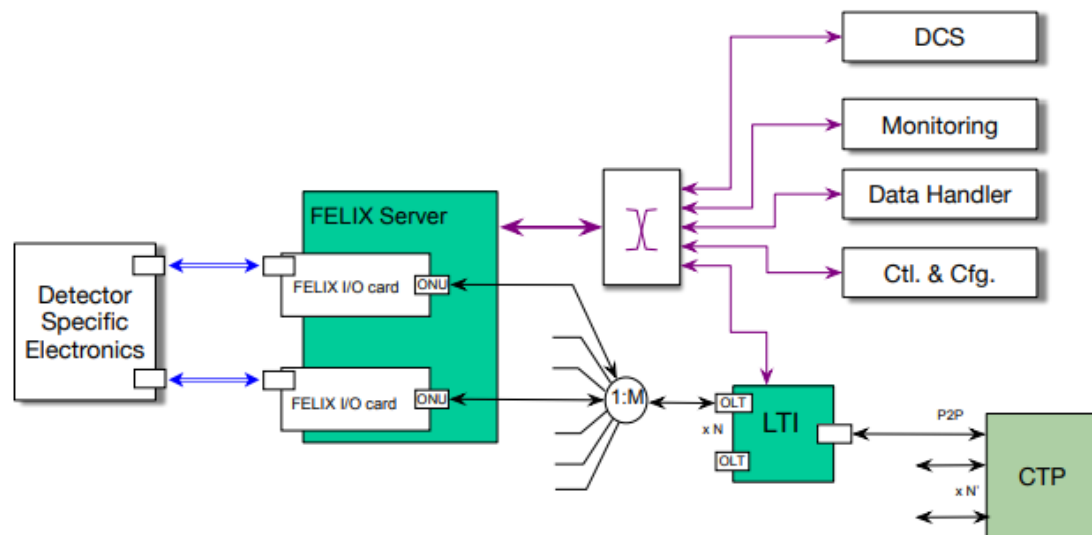
ETL hybrid boards:

- DC-DC converter
- SCA chip for slow control
- lpGBT
- VTRx+



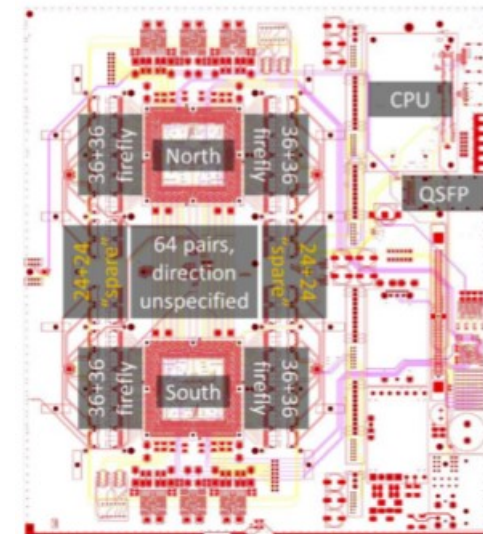
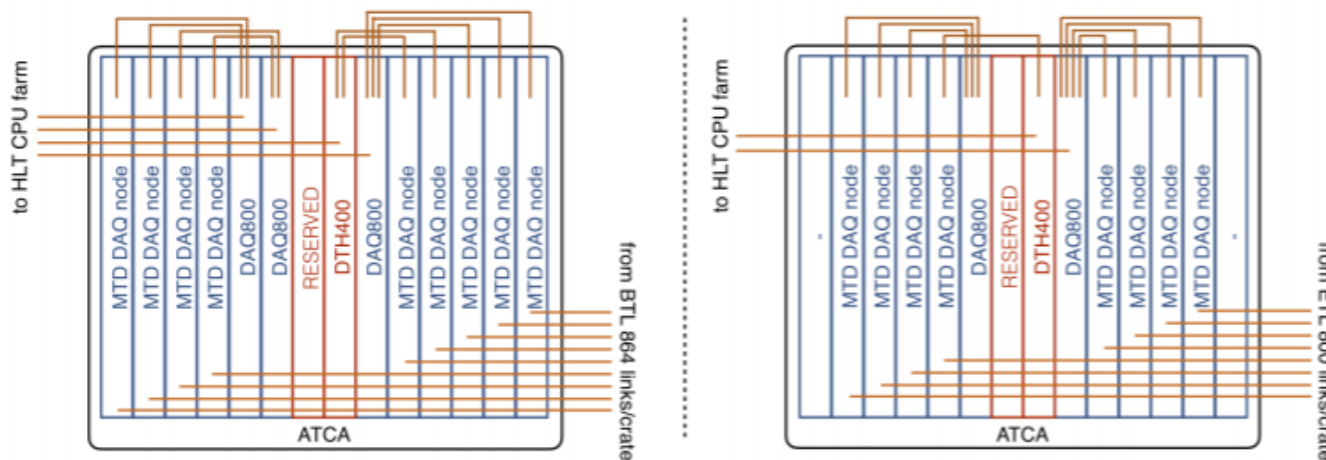
The FELIX (Front End Link Exchange) board will be common to all ATLAS phase-II detectors and it will interface with most of the ATLAS systems:

- Data Handler → Event builder
- Detector Control System (DCS): LV current, temperature,...
- Timing, trigger and control
- On-line monitoring



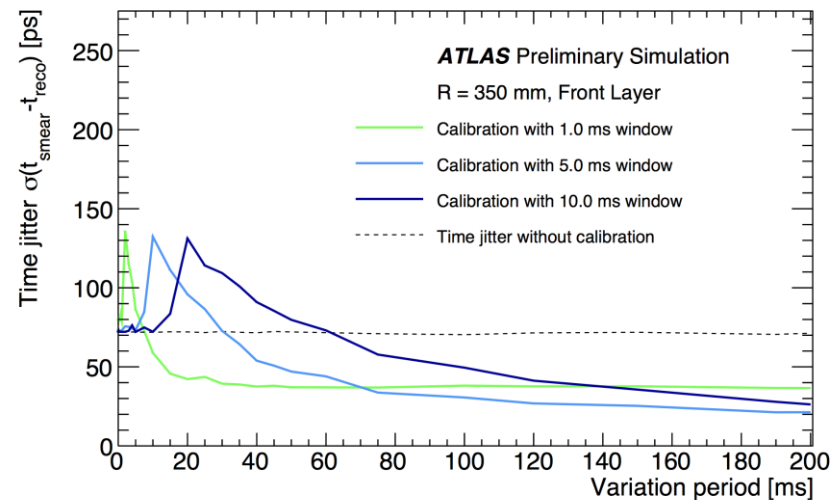
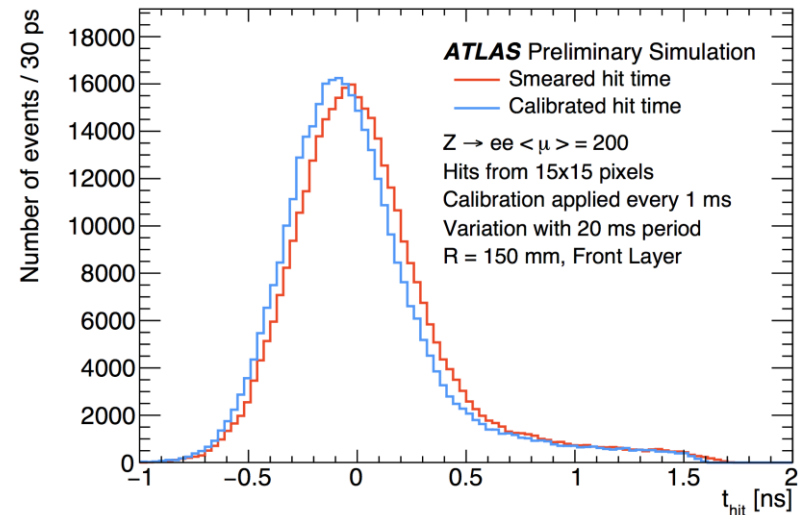
Based on advanced telecommunications architecture (ATCA) with centrally defined CMS specifications:

- The interface to the central Timing and Control and DAQ systems is provided by the data trigger hub (DTH400) and additional data bandwidth to the DAQ system is provided by a DAQ800 board.
- Unpacking and processing of the data received from the front-end will be accomplished by the MTD back-end (Serenity) boards positioned in node slot

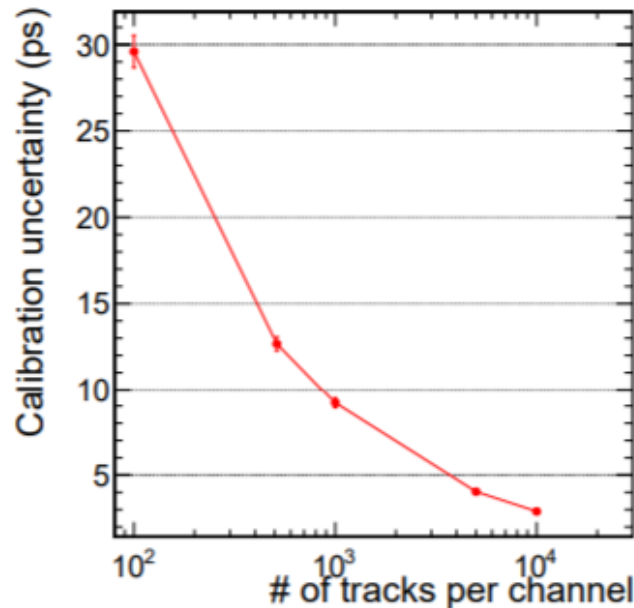
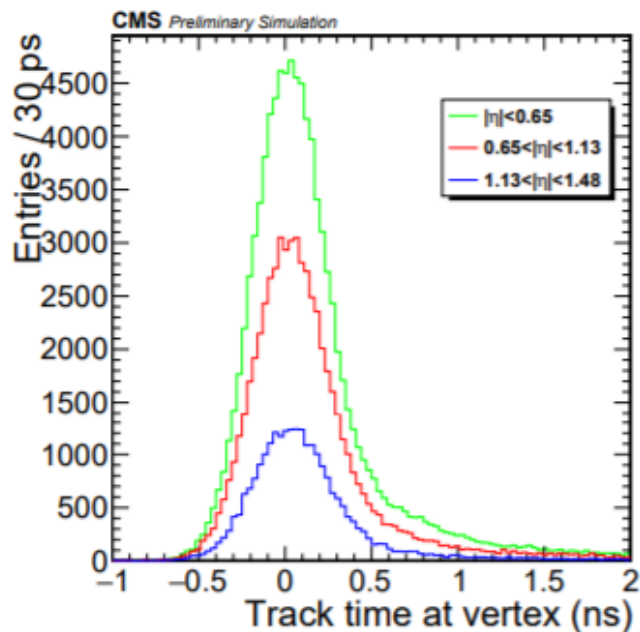


Serenity board

- Static and dynamic contributions to the clock can affect the time resolution of the detector:
  - Static: time-of-flight, non-uniform clock propagation paths within an ASIC.
  - Dynamic: high-frequency jitter, noise in the flex cables, and low frequency day/night temperature changes
- On-line measurement of the average hit time per ASIC at a high trigger rate in the back-end electronics to take into account dynamic contributions.
- The hit time will be averaged during  $\sim 20$  ms and later on the correction will be applied offline.



- The time offsets of the MTD channels can be inter-calibrated using all the tracks collected by the CMS high level trigger.
- At 1 kHz high level trigger rate, 1000-10000 tracks per channel (BTL) will be collected in around 20 or 200 s, providing the possibility of frequent and granular calibrations.
- These calibration constants can be made available for the prompt reconstruction of the events and thus applied offline.





# CONCLUSIONS

- ATLAS and CMS upgrade for HL-LHC foresees novel precision timing detectors with target 30-50 ps time resolution per track.
- Novel LGAD sensors are the baseline technology for ATLAS HGTD and CMS ETL while LYSO and SiPM is the baseline technology for CMS BTL.
- On-detector electronics will be based on common lpGBT and VTRx+ electronics for phase-II upgrade. Dedicated front-end ASICs ALTIROC (HGTD), ETROC (ETL) and TOFHIR (BTL) are under development.
- Off-detector back-end will be based on common FELIX boards for ATLAS HGTD while common (DTH and DAQ800) CMS boards and dedicated DAQ nodes will be used for MTD.
- CMS MTD Technical Design Report was recently (2019) approved.
- ATLAS HGTD Technical Design Report is currently under the approval process.

Thank You